Preliminary Data Sheet



BIPOLAR ANALOG INTEGRATED CIRCUIT

μPC3231GV

5 V AGC AMPLIFIER + VIDEO AMPLIFIER

DESCRIPTION

The μ PC3231GV is silicon monolithic IC designed for use as AGC amplifier for digital CATV, cable modem and digital terrestrial systems. This IC consists of gain control amplifier and video amplifier.

The package is 8-pin SSOP (shrink small outline package) suitable for surface mount.

This IC is manufactured using our 30 GHz f_{max} UHS0 (\underline{U} ltra \underline{H} igh \underline{S} peed Process) silicon bipolar process. This process uses silicon nitride passivation film. This material can protect chip surface from external pollution and prevent corrosion/migration. Thus, this IC has excellent performance, uniformly and reliability.

FEATURES

· Low distortion : $IM_3 = 53.5$ dBc TYP. @ single-ended output, Vout = $105dB\mu V$ ($0.5 V_{P-P}$)/tone

Low noise figure : NF = 5.0 dB TYP. @ Maximum Gain
 Wide AGC dynamic range : GCR = 61 dB TYP. @ input prescribe
 On-chip video amplifier : V_{out} = 1.0 V_{P-P} TYP.@ single-ended output

• Supply Voltage : $V_{CC} = 5.0 \text{ V TYP}$.

· Packaged in 8-pin SSOP suitable for surface mounting.

APPLICATIONS

- · Digital terrestrial TV
- · Digital CATV
- · Cable modem receivers

ORDERING INFORMATION (PLAN)

Part Number	Package	Supplying Form
μPC3231GV-E1	8-pin plastic SSOP (4.45mm(175))	Embossed tape 8mm wide.
		Pin 1 indicates pull-out direction of tape.
		Qty 1kpcs/reel.

Remark To order evaluation samples, please contact your local NEC sales office.

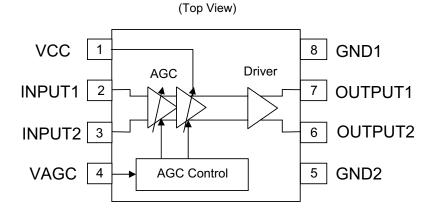
Part number for sample order: $\mu\text{PC3231GV}$

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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Not all devices/types available in every country. Please check with local NEC Electronics sales representative for availability and additional information.

INTERNAL BLOCK DIAGRAM AND PIN CONFIGURATION



PRODUCT LINE-UP OF 5V AGC AMPLIFIER

Part Number	I _{CC} (mA)	GMAX (dB)	GMIN (dB)	GCR (dB)	NF (dB)	IM3 (dBc)	Package
μPC3217GV	23	53	0	53	6.5	50NOTE1	8-pin SSOP (4.45mm(175))
μPC3218GV	23	63	10	53	3.5	50NOTE1	
μPC3219GV	36.5	42.5	0	42.5	9.0	58NOTE1	
μPC3221GV	33	60	10	50	4.2	56NOTE1	
μPC3231GV	36	65	4	61	5.0	53.5NOTE2	

NOTE1 f_1 =44MHz, f_2 =45MHz,Vout=0.7Vp-p/tone,single-ended output NOTE2 f_1 =44MHz, f_2 =45MHz,Vout=0.5Vp-p/tone,single-ended output

PIN EXPLANATIONS

Pin No.	Pin Name	Applied Voltage	Pin Voltage	Function and application	Internal Equivalent Circuit
1	V _{cc}	(V) 4.5 to 5.5	(V) Note	Power supply pin. This pin should be externally equipped with bypass capacitor to minimize ground impedance,	
2	INPUT1	-	1.32	Signal input pins to AGC amplifier. This pin should be coupled with capacitor for DC cut.	AGC
3	INPUT2	-	1.32		2 5 3
4	V _{AGC}	0 to V _{cc}	-	Gain control pin. This pin's bias govern the AGC output level. Minimum Gain at V_{AGC} :0 to 0.1V Maximum Gain at V_{AGC} :2.7 to 3.3V Recommended to use AGC voltage with externally resister (example:1k Ω)	1 AGC AMP
5	GND2	0	-	Ground pin. This pin should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible.	
6	OUTUT2	-	1.91	Signal output pins of video amplifier. This pin should be coupled with capacitor for DC cut.	0
7	OUTUT1	-	1.91		₩-®
8	GND1	0	-	Ground pin. This pin should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as with as possible. All ground pins must be connected together with wide ground pattern to decrease impedance difference.	

Note Pin voltage is measured at V_{CC} =5.0V

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Test Conditions		Rating	Unit
Supply Voltage	V _{cc}	T _A =+25°C		6.0	V
Gain Control Voltage Range	V _{AGC}	T _A =+25°C		0 to V _{cc}	V
Power Dissipation	P _D	T _A =+85°C	Note	250	mW
Storage Temperature	T _{stg}			-55 to+150	°C

Note Mounted on double-sided copper-clad 50 \times 50 $\times 1.6$ mm epoxy glass PWB

RECOMMENDED OPERATING RANGE

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Supply Voltage	V _{CC}		4.5	5.0	5.5	V
Operating Ambient Temperature	T _A	V _{cc} = 4.5 to 5.5 V	-40	+25	+85	°C
Gain Control Voltage Range	V_{AGC}		0	-	3.3	V
Operating Frequency Range	f _(BW)		30	-	90	MHz

ELECTRICAL CHARACTERISTICS

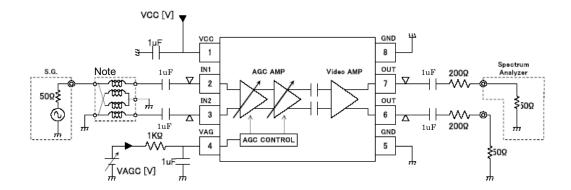
 $(T_A$ =+25°C, V_{CC} = 5V, f = 45MHz, Zs = 50 Ω , Z_L = 250 Ω , single-ended output)

Parameter	Symbol	Test Conditions		MIN.	TYP.	MAX.	Unit
DC Characteristics							
Circuit Current	Icc	V _{CC} =5V,No input signal	Note 1	28	36	44	mA
AGC Voltage High Level	$V_{AGC(H)}$	@ Maximum gain	Note 1	2.7	-	3.3	V
AGC Voltage Low Level	$V_{AGC(L)}$	@ Minimum gain	Note 1	0	-	0.1	>
RF Characteristics							
IF Input Frequency Range	f _(in)	f _c =-3dB @45MHz	Note 1	30	-	90	MHz
Maximum Voltage Gain	G _{MAX}	V _{AGC} =2.7V, Pin= -60dBm	Note 1	62.5	65	67.5	dB
Minimum Voltage Gain	G _{MIN}	V _{AGC} =0.1V, Pin= -30dBm	Note 1	0	4	7	dB
Gain Control Range	GCR _{in}	V _{AGC} =0.1 to 2.7 V	Note 1	55.5	61	-	dB
(input prescribe)							
Gain Control Range	GCR _{out}	$V_{out} = 1.0 V_{p-p}$	Note 1	45	55	-	dB
(output prescribe)							
Output Voltage	V _{out}	$P_{in} = -61 \sim -6 dBm$	Note 1	-	1.0	-	V_{P-P}
Maximum Output Voltage	V _{oclip}	V _{AGC} = 3.0 V	Note 1	2.0	3.3	-	V_{P-P}
Noise Figure	NF	V _{AGC} = 3.0 V	Note 2	-	5.0	6.5	dB
3rd Order Inter-modulation	IM ₃	f ₁ = 44 MHz, f ₂ = 45 MHz,		50	53.5	-	dBc
Distortion		P _{in} = -20 dBm/tone,					
		V _{out} =105dBμV (0.5V _{P-P})/tone	Note 1				
Input impedance	Z _{in}	V _{AGC} =0 V	Note 3	-	1.35//6	-	KΩ//pF

Note 1. By measurement circuit 1

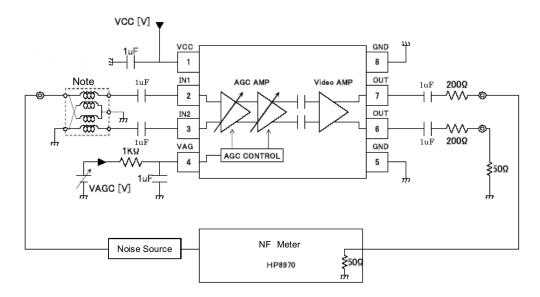
- 2. By measurement circuit 2
- 3. By measurement circuit 3

MEASUREMENT CIRCUIT 1



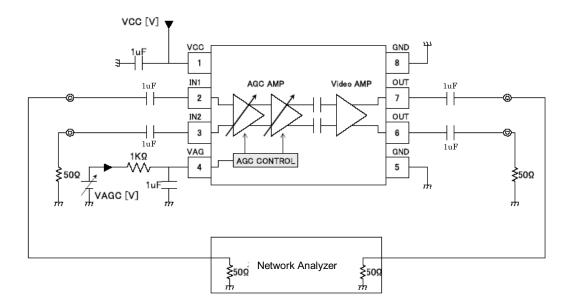
Note Balun Transformer: TOKO 617DB-1674 B4F (Double balanced type)

MEASUREMENT CIRCUIT 2



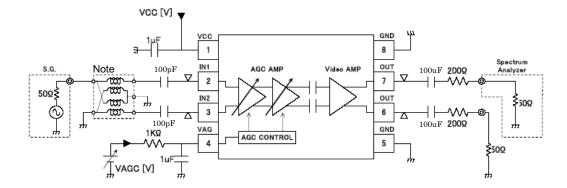
Note Balun Transformer : TOKO 617DB-1674 B4F (Double balanced type)

MEASUREMENT CIRCUIT 3



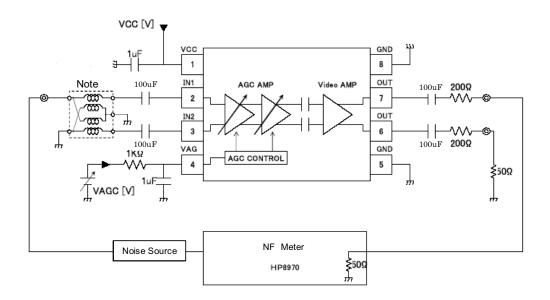
The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

MEASUREMENT CIRCUIT 4 [PRESSURE IMPROVEMENT RECOMMENDATION CIRCUIT]



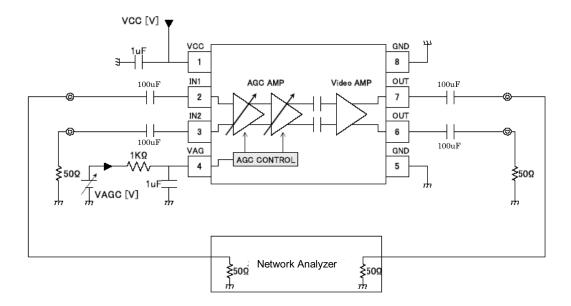
Note Balun Transformer: TOKO 617DB-1674 B4F (Double balanced type)

MEASUREMENT CIRCUIT 5 [PRESSURE IMPROVEMENT RECOMMENDATION CIRCUIT]



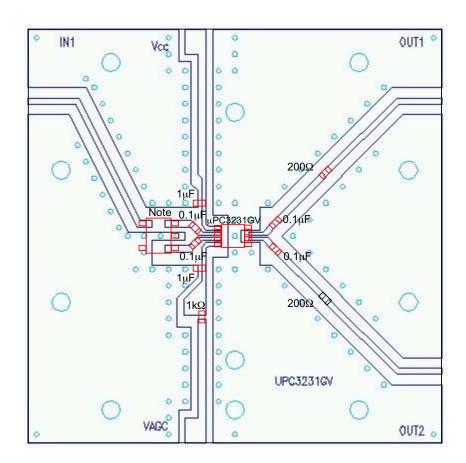
Note Balun Transformer : TOKO 617DB-1674 B4F (Double balanced type)

MEASUREMENT CIRCUIT 6 [PRESSURE IMPROVEMENT RECOMMENDATION CIRCUIT]



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD (MEASUREMENT CIRCUIT 1)



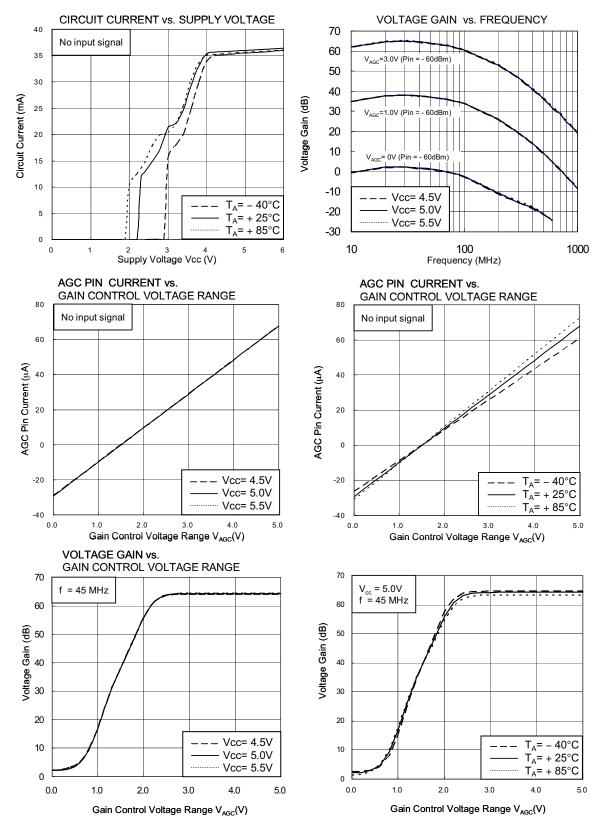
Note Balun Transformer

Remarks

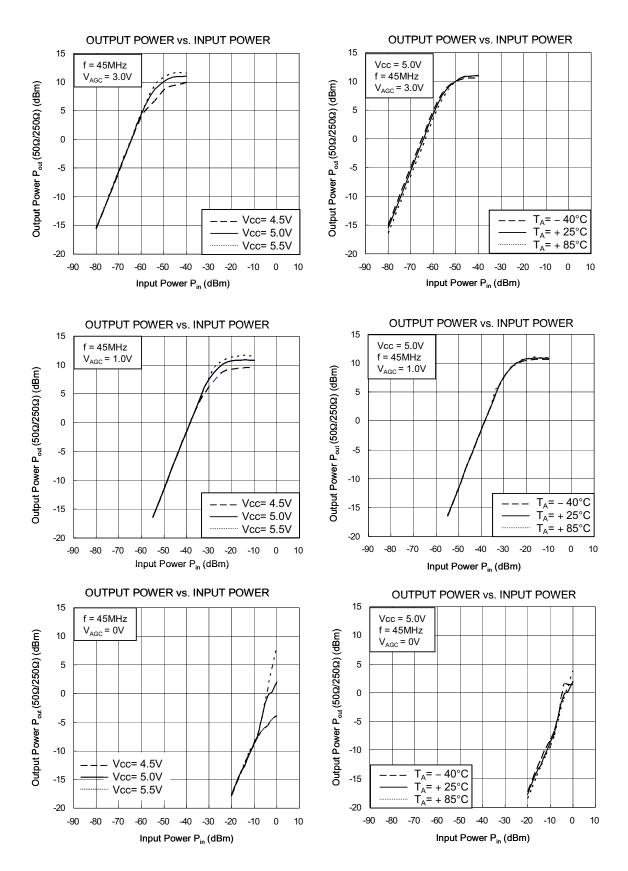
- 1. Back side: GND pattern
- 2. Au plated on pattern
- 3. O: Through hole

TYPICAL CHARACTERISTICS

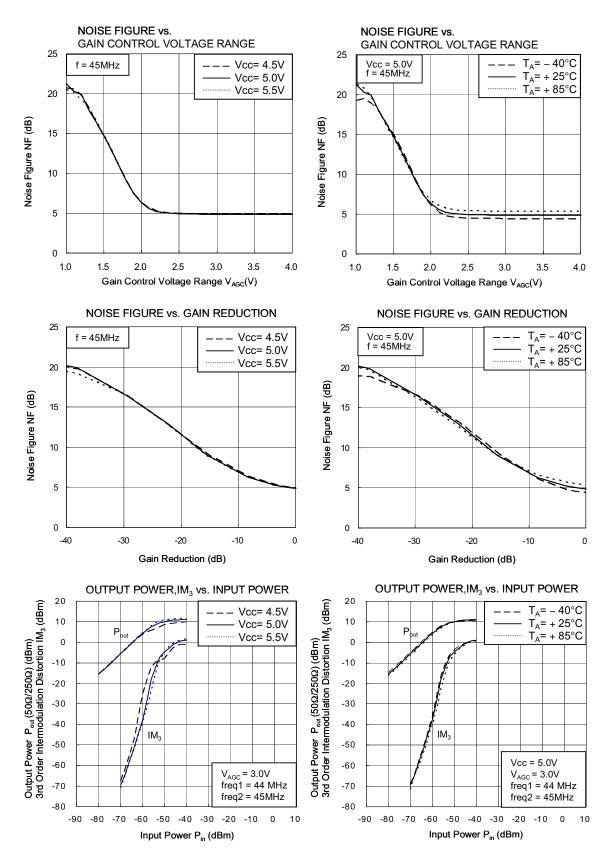
(T_A = +25°C, unless otherwise specified)



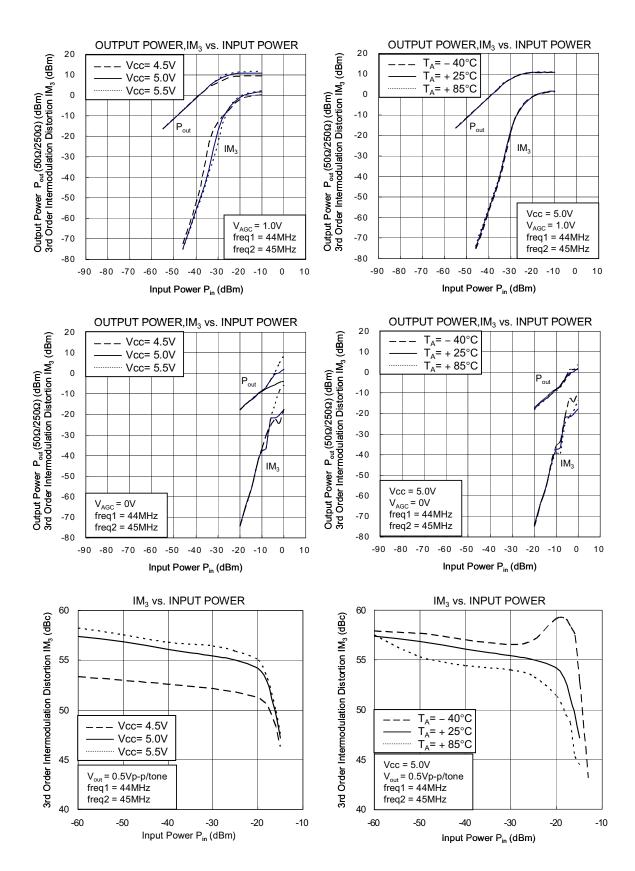
Remark The graphs is indicate nominal characteristics.



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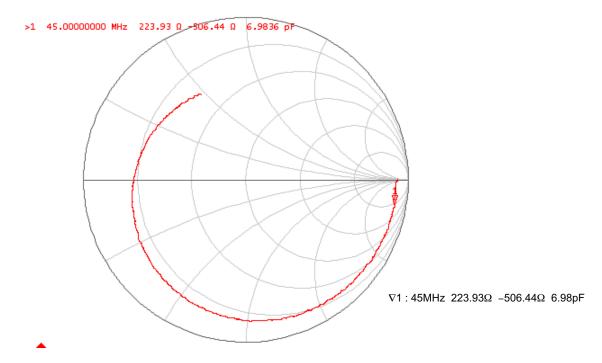
Remark 0The graphs is indicate nominal characteristics.



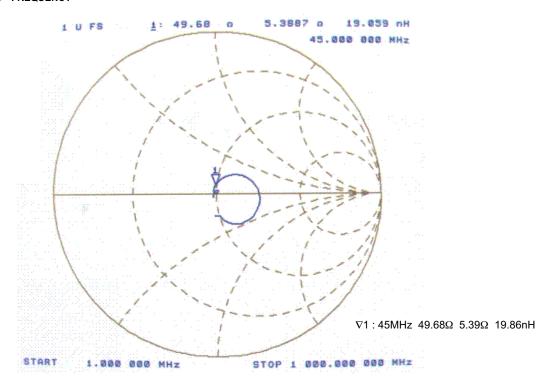
Remark The graphs is indicate nominal characteristics.

S-PARAMETERS (T_A = + 25°C,Vcc = 5V,VAGC=0V)

S11 - FREQUENCY

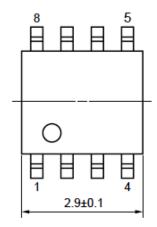


S22 - FREQUENCY



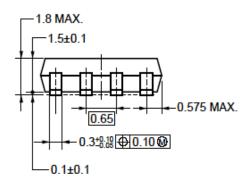
$\mu PC3231GV^*$ PACKAGE DIMENSIONS

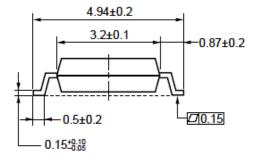
8 PIN PLASTIC SSOP (4.45mm(175)) (Unit:mm)



detail of lead end







RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbo	
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
PBB	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

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